Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	923	257/687	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 21:04
L2	2	"20040065964"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 21:04
S1	213	(semiconductor or chip or die or IC) same (dual or both) with substrate and heat near (spread$3 or transfer or sink) with adhesive	USPAT	OR	OFF	2005/04/08 14:24
S2	256	(semiconductor or chip or die or IC) same (dual or both) with substrate and heat near (spread$3 or transfer or sink) with adhesive	USPAT	OR	ON	2004/09/14 22:21
S3	47	((semiconductor or chip or die or IC) same (dual or both) with substrate and heat near (spread$3 or transfer or sink) with adhesive) and heat near (spread$3 or transfer or sink) with silicon	USPAT	OR	ON	2004/09/14 22:15
S4	38	((semiconductor or chip or die or IC) same (dual or both) with substrate and heat near (spread$3 or transfer or sink) with adhesive) and heat near (spread$3 or transfer or sink) with material with (silicon or silicone)	USPAT	OR	ON	2004/09/14 22:15
S5	370	(semiconductor or chip or die or IC) and heat near (spread$3 or transfer or sink) with material with silicon	USPAT	OR	ON	2004/09/14 22:22
S6	77	(semiconductor or chip or die or IC) and heat near (spread$3 or transfer or sink) near material with silicon	USPAT	OR	ON	2004/09/15 13:47
S7	0	"20030011072"	USPAT	OR	ON	2004/09/15 13:47
S8	1	"20030011072"	US-PGPUB; USPAT	OR	ON	2004/09/15 13:53
S9	2375	bump near electrode	US-PGPUB; USPAT	OR	ON	2004/09/15 13:53
S10	1448	bump near electrode	USPAT	OR	ON	2004/09/15 13:55

S11	1202	(bump near electrode) and bump adj electrode	USPAT	OR	ON	2004/09/15 15:20
S12	2793	257/738	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 18:46
S13	2454	257/706	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 16:00
S14	1914	257/707	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 16:29
S15	3452	257/712	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 17:13
S16	2	"6784541"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 16:40
S17	1	"6784541"	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 16:40
S18	1156	257/720	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 17:30
S19	4103	257/778	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 18:08
S20	1716	257/779	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 18:29
S21	2015	257/780	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 19:18

S22	1097	257/782	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 19:38
S23	1683	257/783	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 20:01
S24	2635	257/784	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 20:21
S25	4795	257/758	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 20:39
S26	2536	257/777	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 21:05
S27	949	438/122	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 22:40
S28	2139	438/108	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 22:45
S29	1009	438/109	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 22:58
S30	3792	361/760	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/15 23:00
S31	3035	257/738	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/18 19:28

S32	23	(semiconductor or chip or die or IC) and heat near (spread$3 or transfer or sink) with (copper or "Cu") with (heat near sensitive near tapes or epoxy with thermal)	USPAT	OR	OFF	2005/04/08 16:32
S33	1570	(semiconductor or chip or die or IC) with (both or dual) with (substrate or carrier or module) and heat near (spread$3 or transfer or sink)	USPAT	OR	OFF	2005/04/08 16:33
S34	1609	(semiconductor or chip or die or IC) with (both or dual) with (substrate or carrier or module) and heat near (spread$3 or transfer$3 or sink)	USPAT	OR	OFF	2005/04/08 17:00
S35	3	"6525943"	USPAT	OR	OFF	2005/04/08 16:36
S36	2	"09463431"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 17:01
S37	0	PCT near JP99 near "01558"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 17:53
S38	1	"5510956".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:02
S39	1	"5585668".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:02
S40	1	"5705850".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:02
S41	1	"5872700".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:02
S42	1	"5880403".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:03
S43	1	"5898224".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:03
S44	1	"5907477".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:03
S45	1	"5969426".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:03
S46	1	"5976912".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:04
S47	1	"6051888".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:04

S48	1	"6087202".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:04
S49	1	"6104093".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:04
S50	1	"6236568".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:05
S51	1	"6246115".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:05
S52	1	"6284569".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:05
S53	1	"6326240".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:05
S54	1	"6326544".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:05
S55	1	"6326696".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:05
S56	1	"6411507".PN.	USPAT; USOCR	OR	OFF	2005/04/08 17:06
S57	2818	257/686	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/04/08 17:53
S58	1144	Dimm	USPAT	OR	OFF	2005/04/08 18:17
S59	878	Dimm and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/04/08 19:22
S60	5	"6525943" or "6627997"	USPAT	OR	OFF	2005/04/08 19:44
S61	0	"5471366".pn. and epoxy	USPAT	OR	OFF	2005/04/08 21:02